xLED

xLED-XIT-7050 Pin Fin LED Heat Sink Φ70mm for Xicato

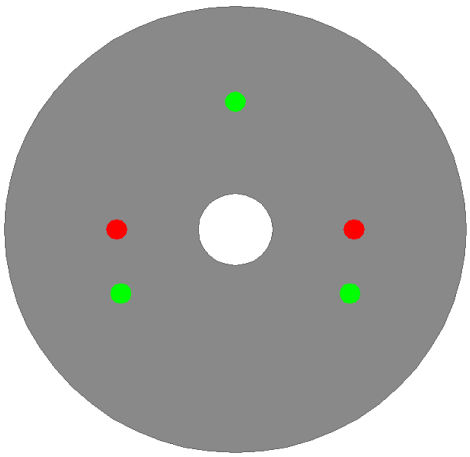
Features VS Benefits

* The xLED-XIT-7050 Xicato Pin Fin LED Heat Sinks are specifically designed for luminaires using the Xicato LED engines.
* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
* For spotlight and downlight designs from 1,000 to 2,600 lumen.
* Thermal resistance range Rth 3.13°C/W.
* Modular design with mounting holes foreseen for direct mounting of Xicato XSA/ XIM/ XTM modules.
* Diameter 70.0mm - standard height 50.0mm,Other heights on request.
* Forged from highly conductive aluminum.

Zhaga LED engine and radiator assembly is a unified future international standardization

* Below you find an overview of Seoul COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
* In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.

XICATO



Xicato LED Modules directly Mounting Options

Xicato XSM LED modules name :

XSM8027-xxxx ; XSM9530-xxxx ;
XSM8030-xxxx ; XSM9540-xxxx ;
XSM8040-xxxx ; XSMV830-xxxx ;
XSM9527-xxxx ;

Direct mounting with 3 screwsM3 x 12mm;
Green indicator marks.

Xicato XIM LED modules name :

XIM198027-xxx ; XIM198040-xxx ; XIM09-V9xxxxxx ;
XIM198030-xxx ; XIM19V830-xxx ;
XIM198035-xxx ; XIM0980 xxxxxx ;

Direct mounting with 3 screws M3 x 20mm;
Green indicator marks.

Xicato XTM LED modules:

XTM19-8027-xxx ; XTM19-8040-xxx ; XTM0995 xxxxxx ;
XTM19-8030-xxx ; XTM19-V830-xxx ;
XTM19-8035-xxx ; XTM09-V9xxxxxx ;

Direct mounting with 3 screws M3 x 10mm;
Green indicator marks.
Direct mounting by Zhaga mounting holes with 2 screws M3 x 8mm;
Red indicator marks.

Tel:+86-769-39023131
Fax:+86-(020)28819702 ext:22122
Email:sales@mingfatech.com
Http://www.heatsinkled.com
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Mingfa TECH

xLED-XIT-7050 Pin Fin LED Heat Sink Φ70mm for Xicato

Mounting Options and Drawings & Dimensions

Example: xLED-XIT-7050-M3-B-1

Example: xLED-XIT-7050-M3-[1]-[2]

[1] Anodising Color

B-Black

C-Clear

Z-Custom

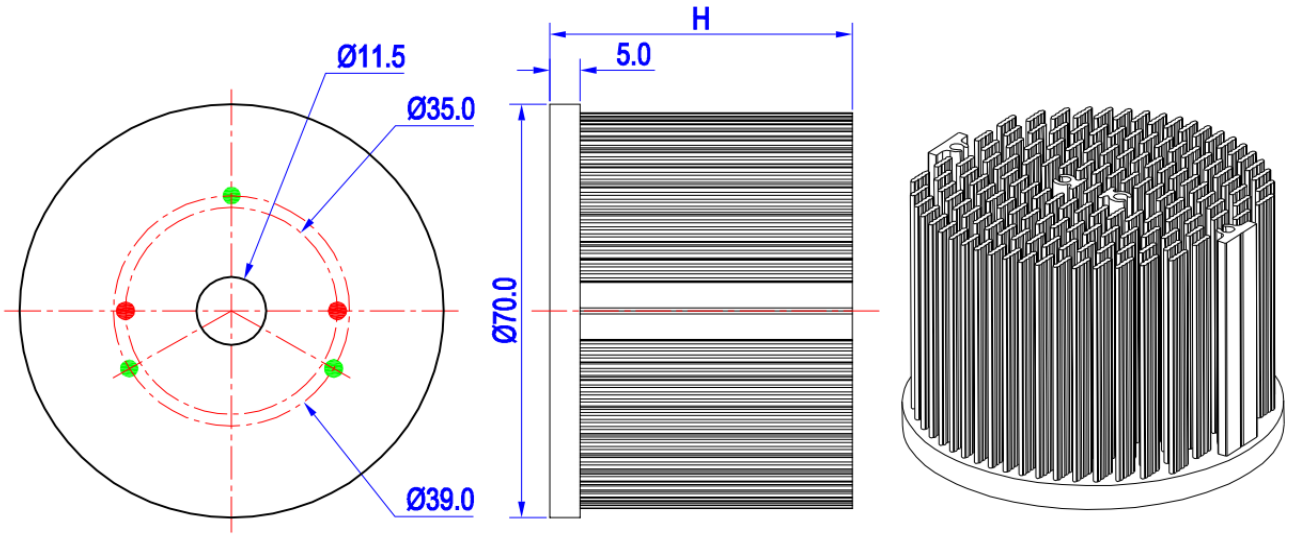
[2] Mounting Options - see graphics for details Combinations available

Ex.order code - 12 means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	PART NUMBER	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
N	xLED-XIT-7050-M3-#-N	M3	6.5mm	39.0mm/ 3-@120°
1	xLED-XIT-7050-M3-#-1	M3	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)
2	xLED-XIT-7050-M3-#-2	M3	Φ11.5mm	Through-Hole



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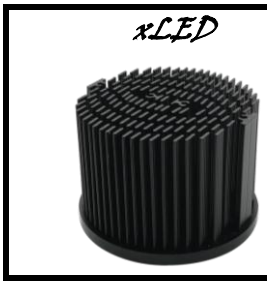
The product deta table



Model No.	**xLED-XIT-7050**
Heatsink Size	**Φ70xH50mm**
Heatsink Material	**AL1070**
Finish	**Black Anodized**
Weight (g)	**150.0**
Dissipated power (Ths-amb,50℃)	**16.0 (W)**
Cooling surface area (mm^2)	**91577**
Thermal Resistance (Rhs-amb)	**3.13 (°C/W)**

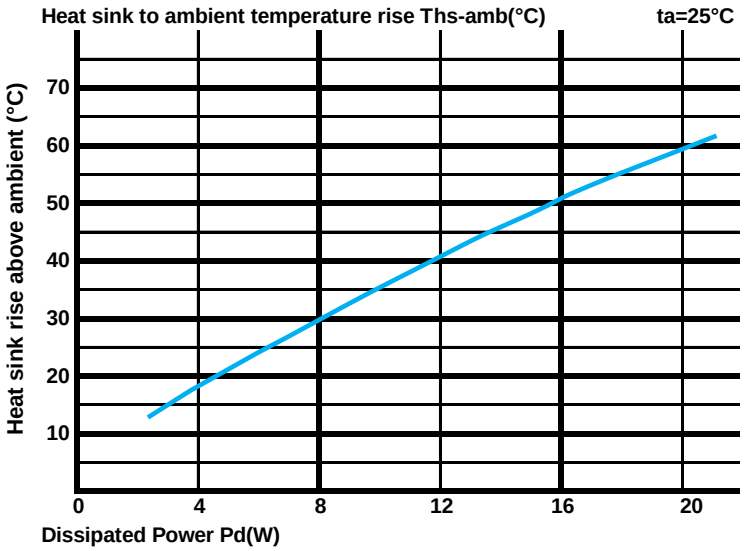
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

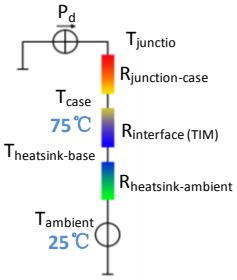
Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		xLED-XIT-7050	
Dissipated Power Pd(W)	4.0	4.25	17.0
	8.0	3.63	29.0
	12.0	3.33	40.0
	16.0	3.13	50.0
	20.0	2.95	59.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease,A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: θ =(Ths−Ta)/Pd

θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface\ (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface\ (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point.Thus, the following formula is also used:

$T_{junction}=(R_{junction-case}+R_{case-ambient})\cdot Pd+T_{ambient}$

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